

Product Change Notification - KSRA-23MARA638

Date: 02 Aug 2017
Product Category: Binary and BCD A/D Converters; Dual Slope A/D Converters
Notification subject: CCB 3043 Initial Notice: Qualification of GTK as a new assembly site for selected products available in 24L SOIC package.
Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of GTK as a new assembly site for selected products available in 24L SOIC package.

Pre Change:

Assembled at ANAP Assembly Site using 8290 die attach material

Post Change:

Assembled at GTK Assembly Site using EN-4900GC die attach material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ANAP Assembly Site	GTK Assembly Site
Wire material	Gold (Au) Wire	Gold (Au) Wire
Die attach material	8290	EN-4900GC
Molding compound material	G600	G600
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on time delivery performance by qualifying GTK as new assembly site

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

November 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2017					-->	November 2017				
	31	32	33	34	35		44	45	46	47	48
Workweek											
Initial PCN Issue Date	X										
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

August 02, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-23MARA638_Affected CPN.pdf](#)
- [PCN_KSRA-23MARA638_Qual Plan.pdf](#)
- [PCN_KSRA-23MARA638_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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KSRA-23MARA638-CCB 3025 Initial Notice: Qualification of GTK as new assembly site for selected products available in 248L SOIC package.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-23MARA638
CATALOG_PART_NBR
TC14433ACOG
TC14433AEOG
TC14433COG
TC14433EOG
TC510COG
TC510COG713
TC510EOG
TC510EOG713